

| L Number | Hits  | Search Text   | DB                             | Time stamp          |
|----------|-------|---|--------------------------------|---------------------|
| 1        | 20704 | "double side polishing" or DSP  | USPAT;<br>EPO; JPO;<br>IBM_TDB | 2003/03/24<br>15:22 |
| 2        | 2183  | (grinding or grind or grinded) and (edge or circumference ) and (polished or polishing or polish) and etch\$3   | USPAT;<br>EPO; JPO;<br>IBM_TDB | 2003/03/24<br>15:53 |
| 3        | 30    | ("double side polishing" or DSP) and ((grinding or grind or grinded) and (edge or circumference ) and (polished or polishing or polish) and etch\$3)                  | USPAT;<br>EPO; JPO;<br>IBM_TDB | 2003/03/24<br>15:24 |
| 4        | 432   | (grinding or grind or grinded) and (edge or circumference ) and (polished or polishing or polish) and etch\$3 and (testing ot testedor metrology)                     | USPAT;<br>EPO; JPO;<br>IBM_TDB | 2003/03/24<br>16:02 |
| 5        | 52    | ((grinding or grind or grinded) and (edge or circumference ) and (polished or polishing or polish) and etch\$3 and (testing ot testedor metrology)) and 438/\$.ccls.  | USPAT;<br>EPO; JPO;<br>IBM_TDB | 2003/03/24<br>16:00 |
| 6        | 192   | ((grinding or grind or grinded) and (edge or circumference ) and (polished or polishing or polish) and etch\$3 and (testing ot testedor metrology)) and semiconductor | USPAT;<br>EPO; JPO;<br>IBM_TDB | 2003/03/24<br>16:00 |
| 7        | 271   | (grinding or grind or grinded) and (edge or circumference ) and (polished or polishing or polish) and etch\$3 and (cluster or module)                                 | USPAT;<br>EPO; JPO;<br>IBM_TDB | 2003/03/24<br>16:52 |
| 9        | 1     | 6309279.pn.   | USPAT;<br>EPO; JPO;<br>IBM_TDB | 2003/03/24<br>16:50 |
| 11       | 13    | (grinding or grind or grinded) and (bevel or beveling ) and (polished or polishing or polish) and etch\$3 and (cluster or module)                                     | USPAT;<br>EPO; JPO;<br>IBM_TDB | 2003/03/24<br>16:54 |
| 12       | 146   | (grinding or grind or grinded) and (bevel or beveling ) and (polished or polishing or polish) and etch\$3   | USPAT;<br>EPO; JPO;<br>IBM_TDB | 2003/03/24<br>16:58 |
| 13       | 30    | ("double side polishing" or DSP) and (grinding or grind or grinded) and (clean or cleaning or rinse or rinsing ) and (polished or polishing or polish) and etch\$3    | USPAT;<br>EPO; JPO;<br>IBM_TDB | 2003/03/24<br>17:01 |